# 450 nA, 9 kHz Op Amp

#### Features:

- Low Quiescent Current: 450 nA (typical)
- Gain Bandwidth Product: 9 kHz (typical)
- Supply Voltage Range: 1.4V to 6.0V
- · Rail-to-Rail Input and Output
- · Unity Gain Stable
- Slew Rate: 3V/ms (typical)
- Extended Temperature Range: -40°C to +125°C
- No Phase Reversal
- Small Packages

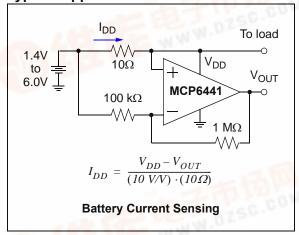
#### **Applications:**

- Portable Equipment
- · Battery Powered System
- Data Acquisition Equipment
- · Sensor Conditioning
- · Battery Current Sensing
- Analog Active Filters

#### **Design Aids:**

- SPICE Macro Models
- FilterLab<sup>®</sup> Software
- Mindi<sup>™</sup> Circuit Designer and Simulator
- Microchip Advanced Part Selector (MAPS)
- · Analog Demonstration and Evaluation Boards
- · Application Notes

**Typical Application** 

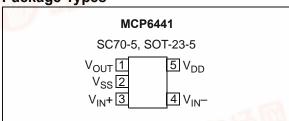


#### **Description:**

The MCP6441 device is a single nanopower operational amplifier (op amp), which has low quiescent current (450 nA, typical) and rail-to-rail input and output operation. This op amp is unity gain stable and has a gain bandwidth product of 9 kHz (typical). These devices operate with a single supply voltage as low as 1.4V. These features make the family of op amps well suited for single-supply, battery-powered applications.

The MCP6441 op amp is designed with Microchip's advanced CMOS process and offered in the 5-pin SC70 and SOT-23 single packages. All devices are available in the extended temperature range, with a power supply range of 1.4V to 6.0V.

**Package Types** 



查询MCP6441供应商 NOTES:

#### 1.0 ELECTRICAL CHARACTERISTICS

## 1.1 Absolute Maximum Ratings †

V <sub>DD</sub> - V <sub>SS</sub>	7.0V
Current at Input Pins	±2 mA
Analog Inputs ( $V_{IN}$ +, $V_{IN}$ -)†† $V_{SS}$ – 1.0V to $V_{SS}$	V <sub>DD</sub> + 1.0V
All Other Inputs and Outputs $V_{SS}$ – 0.3V to $^{\prime}$	V <sub>DD</sub> + 0.3V
Difference Input Voltage	$V_{DD} - V_{SS}$
Output Short-Circuit Current	Continuous
Current at Output and Supply Pins	±30 mA
Storage Temperature65°C	to +150°C
Maximum Junction Temperature (T <sub>J</sub> )	+150°C
ESD Protection on All Pins (HBM; MM) $\geq$	4 kV; 400V

† Notice: Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operational listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

†† See Section 4.1.2 "Input Voltage Limits".

## DC ELECTRICAL SPECIFICATIONS

**Electrical Characteristics**: Unless otherwise indicated,  $V_{DD} = +1.4V$  to +6.0V,  $V_{SS} = GND$ ,  $T_A = +25$ °C,  $V_{CM} = V_{DD}/2$ ,  $V_{OLIT} \approx V_{DD}/2$ ,  $V_{L} = V_{DD}/2$  and  $V_{L} = 100$  to  $V_{L} = 100$ . (Refer to Figure 1-1).

$V_{OUT} \approx V_{DD}/2$ , $V_L = V_{DD}/2$ and $R_L = 1 \text{ M}\Omega$ to $V_L$ . (Refer to Figure 1-1).									
Parameters	Sym	Min	Тур	Max	Units	Conditions			
Input Offset									
Input Offset Voltage	$V_{OS}$	-4.5		+4.5	mV	$V_{CM} = V_{SS}$			
Input Offset Drift with Temperature	$\Delta V_{OS}/\Delta T_{A}$		±2.5		μV/°C	$T_A$ = -40°C to +125°C, $V_{CM} = V_{SS}$			
Power Supply Rejection Ratio	PSRR	65	86	_	dB	$V_{CM} = V_{SS}$			
Input Bias Current and Impedance									
Input Bias Current	Ι <sub>Β</sub>	_	±1	_	pА				
		-	20	-	pА	$T_A = +85$ °C			
			400		pА	T <sub>A</sub> = +125°C			
Input Offset Current	Ios		±1		pА				
Common Mode Input Impedance	$Z_{CM}$		10 <sup>13</sup>   6	1	$\Omega    pF$				
Differential Input Impedance	$Z_{DIFF}$		10 <sup>13</sup>   6		$\Omega \  pF$				
Common Mode									
Common Mode Input Voltage Range	$V_{CMR}$	V <sub>SS</sub> -0.3		V <sub>DD</sub> +0.3	V				
Common Mode Rejection Ratio	CMRR	60	76	_	dB	$V_{CM} = -0.3V$ to 6.3V, $V_{DD} = 6.0V$			
Open-Loop Gain									
DC Open-Loop Gain (Large Signal)	$A_{OL}$	90	110		dB	$V_{OUT} = 0.1V$ to $V_{DD}$ -0.1V $R_L = 10 \text{ k}\Omega$ to $V_L$			
Output									
Maximum Output Voltage Swing	$V_{OL}$ , $V_{OH}$	V <sub>SS</sub> +20	_	V <sub>DD</sub> -20	mV	$V_{DD}$ = 6.0V, $R_L$ = 10 k $\Omega$ 0.5V input overdrive			
Output Short-Circuit Current	I <sub>SC</sub>	_	±3	_	mA	V <sub>DD</sub> = 1.4V			
		_	±22	_	mA	$V_{DD} = 6.0V$			
Power Supply									
Supply Voltage	$V_{DD}$	1.4	_	6.0	V				
Quiescent Current per Amplifier	IQ	250	450	650	nA	$I_{O} = 0, V_{DD} = 5.0V$			

#### **AC ELECTRICAL SPECIFICATIONS**

<b>Electrical Characteristics:</b> Unless otherwise indicated, $T_A = +25^{\circ}\text{C}$ , $V_{DD} = +1.4\text{V}$ to +6.0V, $V_{SS} = \text{GND}$ , $V_{CM} = V_{DD}/2$ , $V_{OUT} \approx V_{DD}/2$ , $V_L = V_{DD}/2$ , $V_L = 1$ MΩ to $V_L$ and $V_L = 1$ MΩ to $V_L = 1$ (Refer to Figure 1-1).									
Parameters	Sym	Min	Тур	Max	Units	Conditions			
AC Response									
Gain Bandwidth Product	GBWP	_	9	_	kHz				
Phase Margin	PM	_	65	_	0	G = +1 V/V			
Slew Rate	SR	_	3	_	V/ms				
Noise	Noise								
Input Noise Voltage	E <sub>ni</sub>	_	5	_	µVр-р	f = 0.1 Hz to 10 Hz			
Input Noise Voltage Density	e <sub>ni</sub>	_	190	_	nV/√Hz	f = 1 kHz			
Input Noise Current Density	i <sub>ni</sub>	_	0.6	_	fA/√Hz	f = 1 kHz			

#### TEMPERATURE SPECIFICATIONS

<b>Electrical Characteristics:</b> Unless otherwise indicated, $V_{DD} = +1.4V$ to +6.0V and $V_{SS} = GND$ .							
Parameters	Sym	Min	Тур	Max	Units	Conditions	
Temperature Ranges							
Operating Temperature Range	T <sub>A</sub>	-40	_	+125	°C	Note 1	
Storage Temperature Range	T <sub>A</sub>	-65	_	+150	°C		
Thermal Package Resistances							
Thermal Resistance, 5L-SC70	$\theta_{\sf JA}$	_	331	_	°C/W		
Thermal Resistance, 5L-SOT-23	$\theta_{\sf JA}$	_	220.7	_	°C/W		

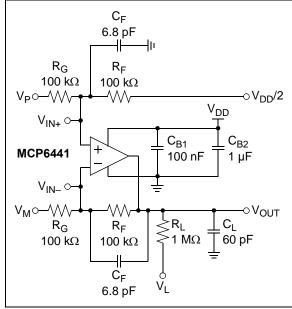
Note 1: The internal junction temperature (T<sub>J</sub>) must not exceed the absolute maximum specification of +150°C.

#### 1.2 Test Circuits

The circuit used for most DC and AC tests is shown in Figure 1-1. This circuit can independently set  $V_{CM}$  and  $V_{OUT}$  (see Equation 1-1). Note that  $V_{CM}$  is not the circuit's Common Mode voltage ((V\_P + V\_M)/2), and that  $V_{OST}$  includes  $V_{OS}$  plus the effects (on the input offset error,  $V_{OST}$ ) of the temperature, CMRR, PSRR and  $A_{OL}$ .

#### **EQUATION 1-1:**

$$\begin{split} G_{DM} &= R_F/R_G \\ V_{CM} &= (V_P + V_{DD}/2)/2 \\ V_{OST} &= V_{IN-} - V_{IN+} \\ V_{OUT} &= (V_{DD}/2) + (V_P - V_M) + V_{OST}(I + G_{DM}) \\ \end{split}$$
 Where: 
$$\begin{aligned} G_{DM} &= & \text{Differential Mode Gain} & (V/V) \\ V_{CM} &= & \text{Op Amp's Common Mode} & (V) \\ & & \text{Input Voltage} \\ \end{aligned}$$
 
$$V_{OST} &= & \text{Op Amp's Total Input Offset} & (mV) \\ & & \text{Voltage} \end{aligned}$$



**FIGURE 1-1:** AC and DC Test Circuit for Most Specifications.

#### 2.0 TYPICAL PERFORMANCE CURVES

**Note:** The graphs and tables provided following this note are a statistical summary based on a limited number of samples and are provided for informational purposes only. The performance characteristics listed herein are not tested or guaranteed. In some graphs or tables, the data presented may be outside the specified operating range (e.g., outside specified power supply range) and therefore outside the warranted range.

**Note:** Unless otherwise indicated,  $T_A$  = +25°C,  $V_{DD}$  = +1.4V to +6.0V,  $V_{SS}$  = GND,  $V_{CM}$  =  $V_{DD}/2$ ,  $V_{OUT} \approx V_{DD}/2$ ,  $V_L$  =  $V_{DD}/2$ ,  $R_L$  = 1 M $\Omega$  to  $V_L$  and  $C_L$  = 60 pF.

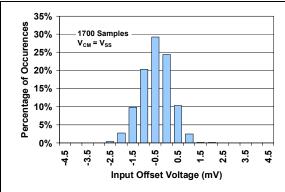


FIGURE 2-1: Input Offset Voltage.

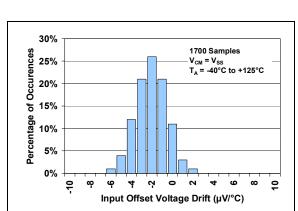
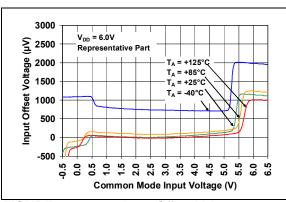
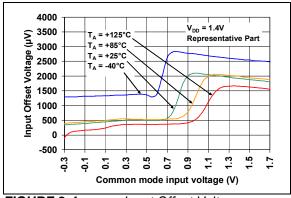


FIGURE 2-2: Input Offset Voltage Drift.



**FIGURE 2-3:** Input Offset Voltage vs. Common Mode Input Voltage with  $V_{DD} = 6.0V$ .



**FIGURE 2-4:** Input Offset Voltage vs. Common Mode Input Voltage with  $V_{DD} = 1.4V$ .

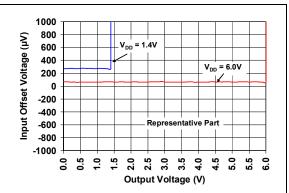


FIGURE 2-5: Input Offset Voltage vs. Output Voltage.

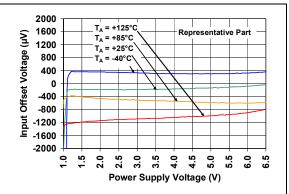


FIGURE 2-6: Input Offset Voltage vs. Power Supply Voltage.

#### 查询MCP6441供应商

**Note:** Unless otherwise indicated,  $T_A = +25^{\circ}C$ ,  $V_{DD} = +1.4V$  to +6.0V,  $V_{SS} = GND$ ,  $V_{CM} = V_{DD}/2$ ,  $V_{OUT} \approx V_{DD}/2$ ,  $V_L = V_{DD}/2$ ,  $R_L = 1$  M $\Omega$  to  $V_L$  and  $C_L = 60$  pF.

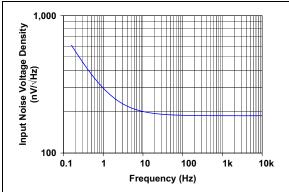


FIGURE 2-7: vs. Frequency.

Input Noise Voltage Density

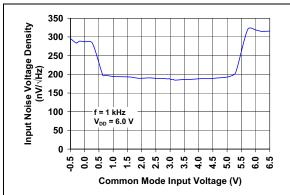


FIGURE 2-8: Input Noise Voltage Density vs. Common Mode Input Voltage.

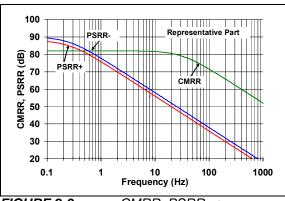


FIGURE 2-9: Frequency.

CMRR, PSRR vs.

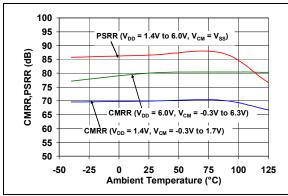


FIGURE 2-10: CMRR, PSRR vs. Ambient Temperature.

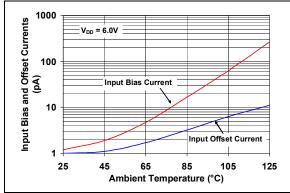


FIGURE 2-11: Input Bias, Offset Current vs. Ambient Temperature.

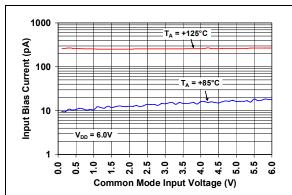
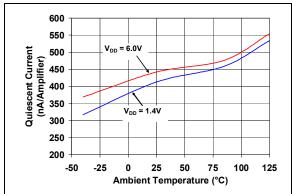


FIGURE 2-12: Input Bias Current vs. Common Mode Input Voltage.

**Note:** Unless otherwise indicated,  $T_A = +25^{\circ}C$ ,  $V_{DD} = +1.4V$  to +6.0V,  $V_{SS} = GND$ ,  $V_{CM} = V_{DD}/2$ ,  $V_{OUT} \approx V_{DD}/2$ ,  $V_L = V_{DD}/2$ ,  $R_L = 1$  M $\Omega$  to  $V_L$  and  $C_L = 60$  pF.



**FIGURE 2-13:** Quiescent Current vs. Ambient Temperature.

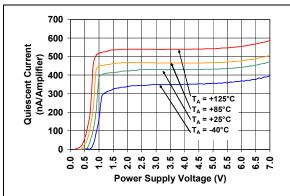
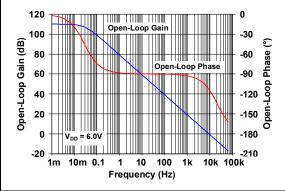
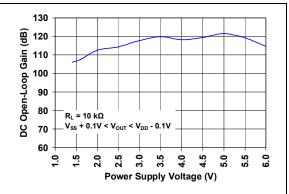


FIGURE 2-14: Quiescent Current vs. Power Supply Voltage.



**FIGURE 2-15:** Open-Loop Gain, Phase vs. Frequency.



**FIGURE 2-16:** DC Open-Loop Gain vs. Power Supply Voltage.

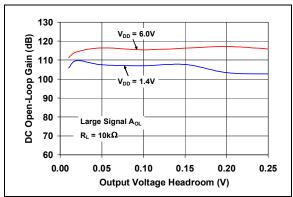
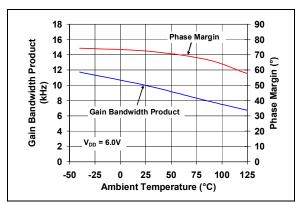


FIGURE 2-17: DC Open-Loop Gain vs. Output Voltage Headroom.



**FIGURE 2-18:** Gain Bandwidth Product, Phase Margin vs. Ambient Temperature.

#### 查询MCP6441供应商

**Note:** Unless otherwise indicated,  $T_A = +25^{\circ}C$ ,  $V_{DD} = +1.4V$  to +6.0V,  $V_{SS} = GND$ ,  $V_{CM} = V_{DD}/2$ ,  $V_{OUT} \approx V_{DD}/2$ ,  $V_L = V_{DD}/2$ ,  $R_L = 1$  M $\Omega$  to  $V_L$  and  $C_L = 60$  pF.

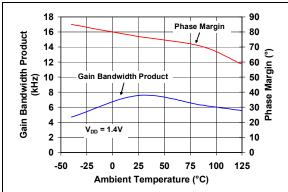


FIGURE 2-19: Gain Bandwidth Product, Phase Margin vs. Ambient Temperature.

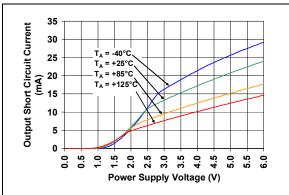


FIGURE 2-20: Output Short Circuit Current vs. Power Supply Voltage.

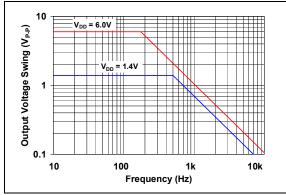
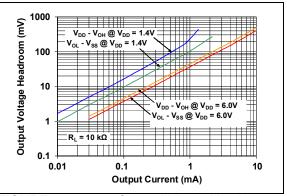


FIGURE 2-21: Output Voltage Swing vs. Frequency.



**FIGURE 2-22:** Output Voltage Headroom vs. Output Current.

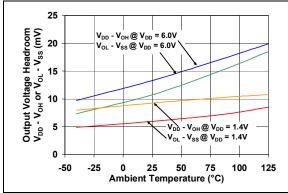


FIGURE 2-23: Output Voltage Headroom vs. Ambient Temperature.

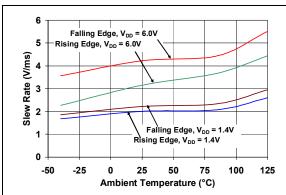


FIGURE 2-24: Slew Rate vs. Ambient Temperature.

**Note:** Unless otherwise indicated,  $T_A = +25$ °C,  $V_{DD} = +1.4V$  to +6.0V,  $V_{SS} = GND$ ,  $V_{CM} = V_{DD}/2$ ,  $V_{OUT} \approx V_{DD}/2$ ,  $V_L = V_{DD}/2$ ,  $R_L = 1$  M $\Omega$  to  $V_L$  and  $C_L = 60$  pF.

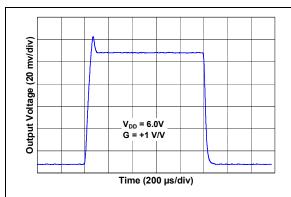


FIGURE 2-25: Small Signal Non-Inverting Pulse Response.

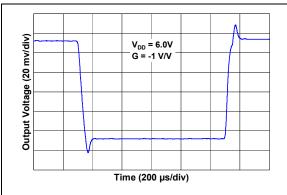


FIGURE 2-26: Small Signal Inverting Pulse Response.

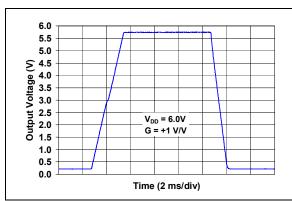


FIGURE 2-27: Large Signal Non-Inverting Pulse Response.

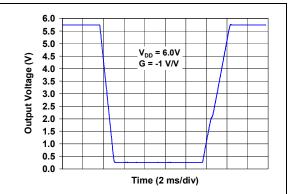


FIGURE 2-28: Large Signal Inverting Pulse Response.

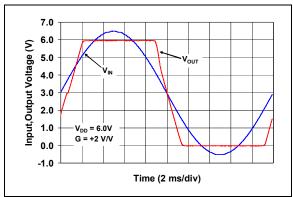


FIGURE 2-29: The MCP6441 Device Shows No Phase Reversal.

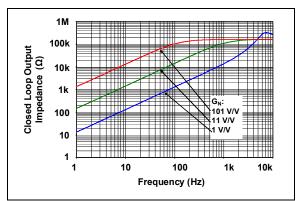
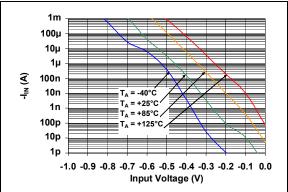


FIGURE 2-30: Closed Loop Output Impedance vs. Frequency.

#### 查询MCP6441供应商

Note: Unless otherwise indicated,  $T_A = +25^{\circ}C$ ,  $V_{DD} = +1.4V$  to +6.0V,  $V_{SS} = GND$ ,  $V_{CM} = V_{DD}/2$ ,  $V_{OUT} \approx V_{DD}/2$ ,  $V_L = V_{DD}/2$ ,  $R_L = 1$  M $\Omega$  to  $V_L$  and  $C_L = 60$  pF.



**FIGURE 2-31:** Measured Input Current vs. Input Voltage (below V<sub>SS</sub>).

#### 3.0 PIN DESCRIPTIONS

Descriptions of the pins are listed in Table 3-1.

TABLE 3-1: PIN FUNCTION TABLE

MCP6441	Symbol	Description
SC70-5, SOT-23-5	Symbol	Description
1	V <sub>OUT</sub>	Analog Output
2	V <sub>SS</sub>	Negative Power Supply
3	V <sub>IN</sub> +	Non-inverting Input
4	V <sub>IN</sub> -	Inverting Input
5	$V_{DD}$	Positive Power Supply

## 3.1 Analog Output (V<sub>OUT</sub>)

The output pin is a low-impedance voltage source.

# 3.2 Power Supply Pins $(V_{DD}, V_{SS})$

The positive power supply (V<sub>DD</sub>) is 1.4V to 6.0V higher than the negative power supply (V<sub>SS</sub>). For normal operation, the other pins are at voltages between V<sub>SS</sub> and V<sub>DD</sub>.

Typically, these parts are used in a single (positive) supply configuration. In this case,  $V_{SS}$  is connected to ground and  $V_{DD}$  is connected to the supply.  $V_{DD}$  will need bypass capacitors.

# 3.3 Analog Inputs (V<sub>IN</sub>+, V<sub>IN</sub>-)

The non-inverting and inverting inputs are high-impedance CMOS inputs with low bias currents.

查询MCP6441供应商 NOTES:

#### 4.0 APPLICATION INFORMATION

The MCP6441 op amp is manufactured using Microchip's state-of-the-art CMOS process, specifically designed for low power applications.

#### 4.1 Rail-to-Rail Input

#### 4.1.1 PHASE REVERSAL

The MCP6441 op amp is designed to prevent phase reversal, when the input pins exceed the supply voltages. Figure 2-29 shows the input voltage exceeding the supply voltage with no phase reversal.

#### 4.1.2 INPUT VOLTAGE LIMITS

In order to prevent damage and/or improper operation of the amplifier, the circuit must limit the voltages at the input pins (see Section 1.1 "Absolute Maximum Ratings †").

The Electrostatic Discharge (ESD) protection on the inputs can be depicted as shown in Figure 4-1. This structure was chosen to protect the input transistors against many, but not all, over-voltage conditions, and to minimize the input bias current  $(I_B)$ .

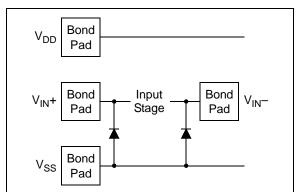


FIGURE 4-1: Simplified Analog Input ESD Structures.

The input ESD diodes clamp the inputs when they try to go more than one diode drop below  $V_{SS}$ . They also clamp any voltages that go well above  $V_{DD}$ ; their breakdown voltage is high enough to allow normal operation, but not low enough to protect against slow over-voltage (beyond  $V_{DD}$ ) events. Very fast ESD events that meet the spec are limited so that damage does not occur.

In some applications, it may be necessary to prevent excessive voltages from reaching the op amp inputs; Figure 4-2 shows one approach to protecting these inputs.

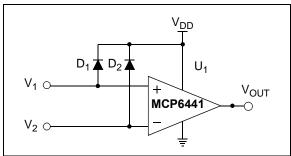


FIGURE 4-2: Protecting the Analog Inputs.

A significant amount of current can flow out of the inputs when the Common Mode voltage ( $V_{CM}$ ) is below ground ( $V_{SS}$ ); See Figure 2-31.

#### 4.1.3 INPUT CURRENT LIMITS

In order to prevent damage and/or improper operation of the amplifier, the circuit must limit the currents into the input pins (see Section 1.1 "Absolute Maximum Ratings †").

Figure 4-3 shows one approach to protecting these inputs. The resistors  $R_1$  and  $R_2$  limit the possible currents in or out of the input pins (and the ESD diodes,  $D_1$  and  $D_2$ ). The diode currents will go through either  $V_{DD}$  or  $V_{SS}$ .

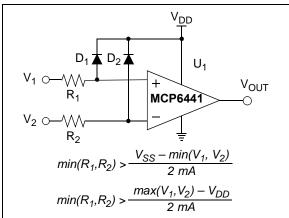


FIGURE 4-3: Protecting the Analog Inputs.

#### 4.1.4 NORMAL OPERATION

The input stage of the MCP6441 op amp uses two differential input stages in parallel. One operates at a low Common Mode input voltage ( $V_{CM}$ ), while the other operates at a high  $V_{CM}$ . With this topology, the device operates with a  $V_{CM}$  up to 300 mV above  $V_{DD}$  and 300 mV below  $V_{SS}$ . The input offset voltage is measured at  $V_{CM} = V_{SS} - 0.3$ V and  $V_{DD} + 0.3$ V, to ensure proper operation.

The transition between the input stages occurs when  $V_{CM}$  is near  $V_{DD} - 0.6V$  (see Figures 2-3 and 2-4). For the best distortion performance and gain linearity, with non-inverting gains, avoid this region of operation.

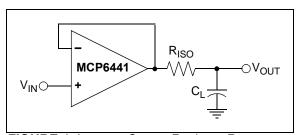
#### 4.2 Rail-to-Rail Output

The output voltage range of the MCP6441 op amp is  $V_{SS}$  + 20 mV (minimum) and  $V_{DD}$  – 20 mV (maximum) when  $R_L$  = 10 k $\Omega$  is connected to  $V_{DD}/2$  and  $V_{DD}$  = 6.0V. Refer to Figures 2-22 and 2-23 for more information.

#### 4.3 Capacitive Loads

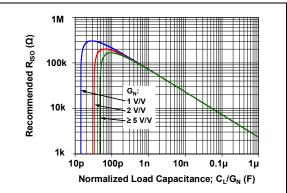
Driving large capacitive loads can cause stability problems for voltage feedback op amps. As the load capacitance increases, the feedback loop's phase margin decreases, and the closed-loop bandwidth is reduced. This produces gain peaking in the frequency response, with overshoot and ringing in the step response. While a unity-gain buffer (G = +1 V/V) is the most sensitive to the capacitive loads, all gains show the same general behavior.

When driving large capacitive loads with the MCP6441 op amp (e.g.,  $> 100 \, \text{pF}$  when  $G = +1 \, \text{V/V}$ ), a small series resistor at the output ( $R_{\text{ISO}}$  in Figure 4-4) improves the feedback loop's phase margin (stability) by making the output load resistive at higher frequencies. The bandwidth will be generally lower than the bandwidth with no capacitance load.



**FIGURE 4-4:** Output Resistor, R<sub>ISO</sub> Stabilizes Large Capacitive Loads.

Figure 4-5 gives the recommended  $R_{ISO}$  values for the different capacitive loads and gains. The x-axis is the normalized load capacitance  $(C_L/G_N)$ , where  $G_N$  is the circuit's noise gain. For non-inverting gains,  $G_N$  and the Signal Gain are equal. For inverting gains,  $G_N$  is 1+|Signal Gain| (e.g., -1 V/V gives  $G_N$  = +2 V/V).



**FIGURE 4-5:** Recommended R<sub>ISO</sub> Values for Capacitive Loads.

After selecting  $R_{\rm ISO}$  for your circuit, double-check the resulting frequency response peaking and step response overshoot. Modify  $R_{\rm ISO}$ 's value until the response is reasonable. Bench evaluation and simulations with the MCP6441 SPICE macro model are very helpful.

#### 4.4 Supply Bypass

The MCP6441 op amp's power supply pin ( $V_{DD}$  for single-supply) should have a local bypass capacitor (i.e., 0.01 µF to 0.1 µF) within 2 mm for good high frequency performance. It can use a bulk capacitor (i.e., 1 µF or larger) within 100 mm to provide large, slow currents. This bulk capacitor can be shared with other analog parts.

#### 4.5 PCB Surface Leakage

In applications where low input bias current is critical, Printed Circuit Board (PCB) surface leakage effects need to be considered. Surface leakage is caused by humidity, dust or other contamination on the board. Under low humidity conditions, a typical resistance between nearby traces is  $10^{12}\Omega$ . A 5V difference would cause 5 pA of current to flow, which is greater than the MCP6441 op amp's bias current at +25°C (±1 pA, typical).

The easiest way to reduce surface leakage is to use a guard ring around sensitive pins (or traces). The guard ring is biased at the same voltage as the sensitive pin. An example of this type of layout is shown in Figure 4-6.

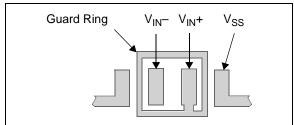


FIGURE 4-6: Example Guard Ring Layout for Inverting Gain.

- 1. Non-inverting Gain and Unity-Gain Buffer:
  - a) Connect the non-inverting pin (V<sub>IN</sub>+) to the input with a wire that does not touch the PCB surface.
  - b) Connect the guard ring to the inverting input pin (V<sub>IN</sub>-). This biases the guard ring to the Common Mode input voltage.
- Inverting Gain and Transimpedance Gain Amplifiers (convert current to voltage, such as photo detectors):
  - a) Connect the guard ring to the non-inverting input pin (V<sub>IN</sub>+). This biases the guard ring to the same reference voltage as the op amp (e.g., V<sub>DD</sub>/2 or ground).
  - b) Connect the inverting pin (V<sub>IN</sub>-) to the input with a wire that does not touch the PCB surface.

#### 4.6 Application Circuits

#### 4.6.1 BATTERY CURRENT SENSING

The MCP6441 op amp's Common Mode Input Range, which goes 0.3V beyond both supply rails, supports their use in high-side and low-side battery current sensing applications. The low quiescent current (450 nA, typical) helps prolong battery life, and the rail-to-rail output supports detection of low currents.

Figure 4-7 shows a high side battery current sensor circuit. The  $10\Omega$  resistor is sized to minimize power losses. The battery current (I\_DD) through the  $10\Omega$  resistor causes its top terminal to be more negative than the bottom terminal. This keeps the Common Mode input voltage of the op amp below V\_DD, which is within its allowed range. The output of the op amp will also be below V\_DD, within its Maximum Output Voltage Swing specification.

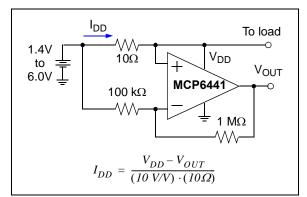


FIGURE 4-7: Battery Current Sensing.

# 4.6.2 PRECISION HALF-WAVE RECTIFIER

The precision half-wave rectifier, which is also known as a super diode, is a configuration obtained with an operational amplifier in order to have a circuit behaving like an ideal diode and rectifier. It effectively cancels the forward voltage drop of the diode in such way that very low level signals can still be rectified, with minimal error. This can be useful for high-precision signal processing. The MCP6441 op amp has high input impedance, low input bias current and rail-to-rail input/output, which makes this device suitable for precision rectifier applications.

Figure 4-8 shows a precision half-wave rectifier and its transfer characteristic. The rectifier's input impedance is determined by the input resistor  $R_1$ . To avoid the loading effect, it must be driven from a low-impedance source.

When  $V_{IN}$  is greater than zero,  $D_1$  is OFF,  $D_2$  is ON, and  $V_{OUT}$  is zero. When  $V_{IN}$  is less than zero,  $D_1$  is ON,  $D_2$  is OFF, and  $V_{OUT}$  is the  $V_{IN}$  with an amplification of  $-R_2/R_1$ .

The rectifier circuit shown in Figure 4-8 has the benefit that the op amp never goes in saturation, so the only thing affecting its frequency response is the amplification and the gain bandwidth product.

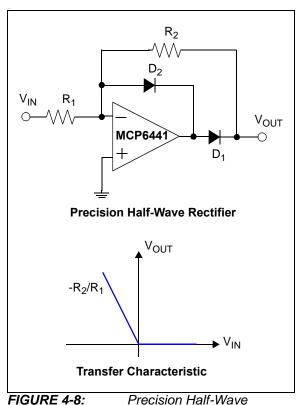


FIGURE 4-8: Rectifier.

#### 4.6.3 INSTRUMENTATION AMPLIFIER

The MCP6441 op amp is well suited for conditioning sensor signals in battery-powered applications. Figure 4-9 shows a two op amp instrumentation amplifier, using the MCP6441 device, that works well for applications requiring rejection of Common Mode noise at higher gains. The reference voltage ( $V_{REF}$ ) is supplied by a low-impedance source. In single supply applications,  $V_{REF}$  is typically  $V_{DD}/2$ .

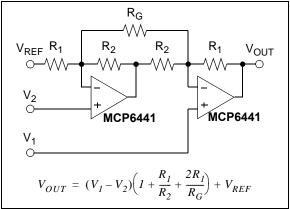


FIGURE 4-9: Two Op Amp Instrumentation Amplifier.

#### 5.0 DESIGN AIDS

Microchip provides the basic design tools needed for the MCP6441 op amp.

#### 5.1 SPICE Macro Model

The latest SPICE macro model for the MCP6441 op amp is available on the Microchip web site at www.microchip.com. The model was written and tested in the official OrCAD (Cadence®) owned PSpice®. For the other simulators, translation may be required.

The model covers a wide aspect of the op amp's electrical specifications. Not only does the model cover voltage, current and resistance of the op amp, but it also covers the temperature and the noise effects on the behavior of the op amp. The model has not been verified outside of the specification range listed in the op amp data sheet. The model behaviors under these conditions cannot ensure it will match the actual op amp performance.

Moreover, the model is intended to be an initial design tool. Bench testing is a very important part of any design and cannot be replaced with simulations. Also, simulation results using this macro model need to be validated by comparing them to the data sheet specifications and characteristic curves.

## 5.2 FilterLab® Software

Microchip's FilterLab software is an innovative software tool that simplifies analog active filter design using op amps. Available at no cost from the Microchip web site at <a href="https:/www.microchip.com/filterlab">www.microchip.com/filterlab</a>, the FilterLab design tool provides full schematic diagrams of the filter circuit with component values. It also outputs the filter circuit in SPICE format, which can be used with the macro model to simulate the actual filter performance.

# 5.3 Mindi™ Circuit Designer and Simulator

Microchip's Mindi Circuit Designer and Simulator aids in the design of various circuits useful for active filter, amplifier and power-management applications. It is a free online circuit designer and simulator, available from the Microchip web site at <a href="https://www.microchip.com/mindi">www.microchip.com/mindi</a>. This interactive circuit designer and simulator enables designers to quickly generate circuit diagrams and simulate circuits. Circuits developed using the Mindi Circuit Designer and Simulator can be downloaded to a personal computer or workstation.

# 5.4 Microchip Advanced Part Selector (MAPS)

MAPS is a software tool that helps semiconductor professionals efficiently identify the Microchip devices that fit a particular design requirement. Available at no cost from the Microchip website at <a href="https://www.microchip.com/maps">www.microchip.com/maps</a>, the MAPS is an overall selection tool for Microchip's product portfolio that includes Analog, Memory, MCUs and DSCs. Using this tool, you can define a filter to sort features for a parametric search of devices and export side-by-side technical comparison reports. Helpful links are also provided for Data Sheets, Purchase and Sampling of Microchip parts.

# 5.5 Analog Demonstration and Evaluation Boards

Microchip offers a broad spectrum of Analog Demonstration and Evaluation Boards that are designed to help you achieve faster time to market. For a complete listing of these boards and their corresponding user's guides and technical information, visit the Microchip web site at www.microchip.com/analogtools.

Some boards that are especially useful are:

- MCP6XXX Amplifier Evaluation Board 1
- MCP6XXX Amplifier Evaluation Board 2
- MCP6XXX Amplifier Evaluation Board 3
- MCP6XXX Amplifier Evaluation Board 4
- · Active Filter Demo Board Kit
- 5/6-Pin SOT-23 Evaluation Board, P/N VSUPEV2

## 查询MCP6441供应商

#### 5.6 Application Notes

The following Microchip Analog Design Note and Application Notes are available on the Microchip web site at <a href="https://www.microchip.com/appnotes">www.microchip.com/appnotes</a>, and are recommended as supplemental reference resources.

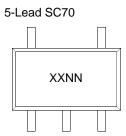
- ADN003 "Select the Right Operational Amplifier for your Filtering Circuits", DS21821
- AN722 "Operational Amplifier Topologies and DC Specifications", DS00722
- AN723 "Operational Amplifier AC Specifications and Applications", DS00723
- AN884 "Driving Capacitive Loads With Op Amps", DS00884
- AN990 "Analog Sensor Conditioning Circuits An Overview", DS00990
- AN1177 "Op Amp Precision Design: DC Errors", DS01177
- AN1228 "Op Amp Precision Design: Random Noise", DS01228
- AN1297 "Microchip's Op Amp SPICE Macro Models", DS01297

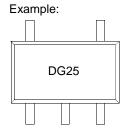
These application notes and others are listed in the design guide:

• "Signal Chain Design Guide", DS21825

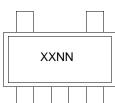
#### 6.0 PACKAGING INFORMATION

#### 6.1 Package Marking Information

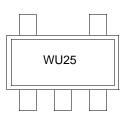












Legend: XX...X Customer-specific information

Y Year code (last digit of calendar year)
YY Year code (last 2 digits of calendar year)
WW Week code (week of January 1 is week '01')

NNN Alphanumeric traceability code

(e3) Pb-free JEDEC designator for Matte Tin (Sn)

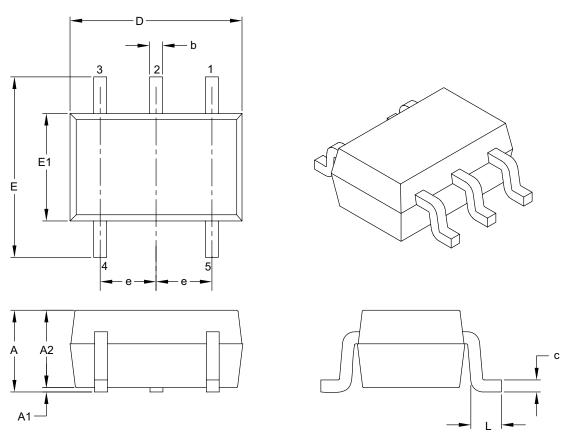
This package is Pb-free. The Pb-free JEDEC designator (e3)

can be found on the outer packaging for this package.

**Note**: In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line, thus limiting the number of available characters for customer-specific information.

## 5-Lead Plastic Small Outline Transistor (LT) [SC70]

**Note:** For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



·	Units		3			
	MIN	NOM	MAX			
Number of Pins	N	5				
Pitch	е	0.65 BSC				
Overall Height	A	0.80	_	1.10		
Molded Package Thickness	A2	0.80	_	1.00		
Standoff	A1	0.00	_	0.10		
Overall Width	E	1.80	2.10	2.40		
Molded Package Width	E1	1.15	1.25	1.35		
Overall Length	D	1.80	2.00	2.25		
Foot Length	L	0.10	0.20	0.46		
Lead Thickness	С	0.08	_	0.26		
Lead Width	b	0.15	_	0.40		

#### Notes:

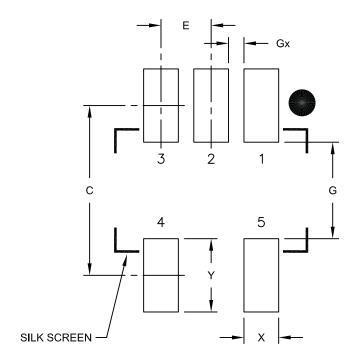
- 1. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.127 mm per side.
- 2. Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing C04-061B

# 5-Lead Plastic Small Outline Transistor (LT) [SC70]

**Note:** For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

	MILLIMETERS					
Dimension	Dimension Limits			MAX		
Contact Pitch	Ш	0.65 BSC				
Contact Pad Spacing	С	2.20				
Contact Pad Width	Х	0.45				
Contact Pad Length	Υ	0.95				
Distance Between Pads	G	1.25				
Distance Between Pads	Gx	0.20				

#### Notes:

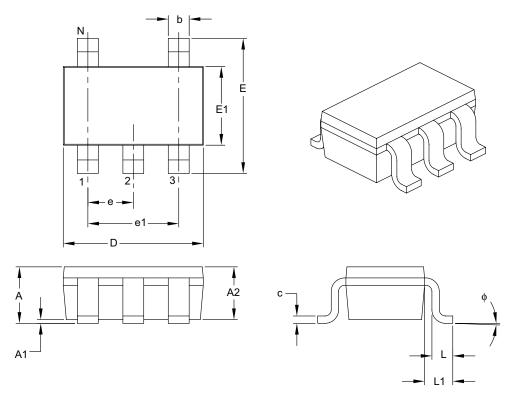
1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2061A

# 5-Lead Plastic Small Outline Transistor (OT) [SOT-23]

**Note:** For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



	U	nits	MILLIMETERS				
	Dimension Lir	nits	MIN	NOM	MAX		
Number of Pins	1	N	5				
Lead Pitch		е	0.95 BSC				
Outside Lead Pitch	e	e1		1.90 BSC			
Overall Height	,	Α	0.90	-	1.45		
Molded Package Thickness	P	۱2	0.89	_	1.30		
Standoff	P	۱1	0.00	_	0.15		
Overall Width	1	Ε	2.20	_	3.20		
Molded Package Width	E	Ξ1	1.30	_	1.80		
Overall Length	1	D	2.70	_	3.10		
Foot Length		L	0.10	_	0.60		
Footprint	L	_1	0.35	_	0.80		
Foot Angle		ф	0°	_	30°		
Lead Thickness		С	0.08	_	0.26		
Lead Width		b	0.20	_	0.51		

#### Notes:

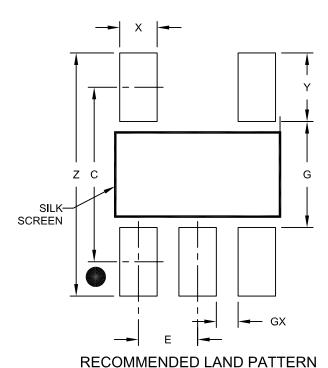
- 1. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.127 mm per side.
- 2. Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing C04-091B

#### 5-Lead Plastic Small Outline Transistor (OT) [SOT-23]

**Note:** For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units **MILLIMETERS** MIN NOM **Dimension Limits** MAX Contact Pitch 0.95 BSC Ε Contact Pad Spacing С 2.80 Contact Pad Width (X5) Х 0.60 Contact Pad Length (X5) Υ 1.10 G 1.70 Distance Between Pads 0.35 Distance Between Pads GX Overall Width 3.90

#### Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2091A

查询MCP6441供应商 NOTES:

# 查询MCP6441供应商 APPENDIX A: REVISION HISTORY

# **Revision A (September 2010)**

• Original Release of this Document.

查询MCP6441供应商 NOTES:

# PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, refer to the factory or the listed sales office.

PART NO. Device Tape and Reel Temperature Package Range

Device:

MCP6441:

Single Op Amp (Tape and Reel) (SC70, SOT-23)

= -40°C to +125°C Temperature Range: E

Package: LT = Plastic Package (SC70), 5-lead

OT = Plastic Small Outline Transistor (SOT-23), 5-lead

Examples:

MCP6441T-E/LT:

Tape and Reel, 5LD SC70 Package

MCP6441T-E/OT: Tape and Reel,

5LD SOT-23 Package

查询MCP6441供应商 NOTES:

#### Note the following details of the code protection feature on Microchip devices:

- · Microchip products meet the specification contained in their particular Microchip Data Sheet.
- Microchip believes that its family of products is one of the most secure families of its kind on the market today, when used in the
  intended manner and under normal conditions.
- There are dishonest and possibly illegal methods used to breach the code protection feature. All of these methods, to our knowledge, require using the Microchip products in a manner outside the operating specifications contained in Microchip's Data Sheets. Most likely, the person doing so is engaged in theft of intellectual property.
- Microchip is willing to work with the customer who is concerned about the integrity of their code.
- Neither Microchip nor any other semiconductor manufacturer can guarantee the security of their code. Code protection does not mean that we are guaranteeing the product as "unbreakable."

Code protection is constantly evolving. We at Microchip are committed to continuously improving the code protection features of our products. Attempts to break Microchip's code protection feature may be a violation of the Digital Millennium Copyright Act. If such acts allow unauthorized access to your software or other copyrighted work, you may have a right to sue for relief under that Act.

Information contained in this publication regarding device applications and the like is provided only for your convenience and may be superseded by updates. It is your responsibility to ensure that your application meets with your specifications. MICROCHIP MAKES NO REPRESENTATIONS OR WARRANTIES OF ANY KIND WHETHER EXPRESS OR IMPLIED, WRITTEN OR ORAL, STATUTORY OR OTHERWISE, RELATED TO THE INFORMATION, INCLUDING BUT NOT LIMITED TO ITS CONDITION, QUALITY, PERFORMANCE, MERCHANTABILITY OR FITNESS FOR PURPOSE. Microchip disclaims all liability arising from this information and its use. Use of Microchip devices in life support and/or safety applications is entirely at the buyer's risk, and the buyer agrees to defend, indemnify and hold harmless Microchip from any and all damages, claims, suits, or expenses resulting from such use. No licenses are conveyed, implicitly or otherwise, under any Microchip intellectual property rights.

#### **Trademarks**

The Microchip name and logo, the Microchip logo, dsPIC, KEELOQ, KEELOQ logo, MPLAB, PIC, PICmicro, PICSTART, PIC<sup>32</sup> logo, rfPIC and UNI/O are registered trademarks of Microchip Technology Incorporated in the U.S.A. and other countries.

FilterLab, Hampshire, HI-TECH C, Linear Active Thermistor, MXDEV, MXLAB, SEEVAL and The Embedded Control Solutions Company are registered trademarks of Microchip Technology Incorporated in the U.S.A.

Analog-for-the-Digital Age, Application Maestro, CodeGuard, dsPICDEM, dsPICDEM.net, dsPICworks, dsSPEAK, ECAN, ECONOMONITOR, FanSense, HI-TIDE, In-Circuit Serial Programming, ICSP, Mindi, MiWi, MPASM, MPLAB Certified logo, MPLIB, MPLINK, mTouch, Omniscient Code Generation, PICC, PICC-18, PICDEM, PICDEM.net, PICkit, PICtail, REAL ICE, rfLAB, Select Mode, Total Endurance, TSHARC, UniWinDriver, WiperLock and ZENA are trademarks of Microchip Technology Incorporated in the U.S.A. and other countries.

SQTP is a service mark of Microchip Technology Incorporated in the U.S.A.

All other trademarks mentioned herein are property of their respective companies.

© 2010, Microchip Technology Incorporated, Printed in the U.S.A., All Rights Reserved.

Printed on recycled paper.

ISBN: 978-1-60932-513-8

Microchip received ISO/TS-16949:2002 certification for its worldwide headquarters, design and wafer fabrication facilities in Chandler and Tempe, Arizona; Gresham, Oregon and design centers in California and India. The Company's quality system processes and procedures are for its PIC® MCUs and dsPIC® DSCs, KEELOO® code hopping devices, Serial EEPROMs, microperipherals, nonvolatile memory and analog products. In addition, Microchip's quality system for the design and manufacture of development systems is ISO 9001:2000 certified.

# QUALITY MANAGEMENT SYSTEM CERTIFIED BY DNV ISO/TS 16949:2002



# **Worldwide Sales and Service**

#### **AMERICAS**

Corporate Office 2355 West Chandler Blvd.

Chandler, AZ 85224-6199 Tel: 480-792-7200 Fax: 480-792-7277 Technical Support:

http://support.microchip.com

Web Address: www.microchip.com

Atlanta

Duluth, GA Tel: 678-957-9614 Fax: 678-957-1455

**Boston** 

Westborough, MA Tel: 774-760-0087 Fax: 774-760-0088

Chicago Itasca. IL

Tel: 630-285-0071 Fax: 630-285-0075

Cleveland

Independence, OH Tel: 216-447-0464 Fax: 216-447-0643

Dallas

Addison, TX Tel: 972-818-7423 Fax: 972-818-2924

Detroit

Farmington Hills, MI Tel: 248-538-2250 Fax: 248-538-2260

Kokomo

Kokomo, IN Tel: 765-864-8360 Fax: 765-864-8387

Los Angeles

Mission Viejo, CA Tel: 949-462-9523 Fax: 949-462-9608

Santa Clara

Santa Clara, CA Tel: 408-961-6444 Fax: 408-961-6445

Toronto

Mississauga, Ontario,

Canada

Tel: 905-673-0699 Fax: 905-673-6509

#### ASIA/PACIFIC

**Asia Pacific Office** 

Suites 3707-14, 37th Floor Tower 6, The Gateway Harbour City, Kowloon Hong Kong

Tel: 852-2401-1200 Fax: 852-2401-3431

Australia - Sydney

Tel: 61-2-9868-6733 Fax: 61-2-9868-6755

China - Beijing

Tel: 86-10-8528-2100 Fax: 86-10-8528-2104

China - Chengdu

Tel: 86-28-8665-5511 Fax: 86-28-8665-7889

China - Chongqing

Tel: 86-23-8980-9588 Fax: 86-23-8980-9500

China - Hong Kong SAR

Tel: 852-2401-1200 Fax: 852-2401-3431

China - Nanjing

Tel: 86-25-8473-2460 Fax: 86-25-8473-2470

China - Qingdao

Tel: 86-532-8502-7355 Fax: 86-532-8502-7205

China - Shanghai

Tel: 86-21-5407-5533 Fax: 86-21-5407-5066

China - Shenyang

Tel: 86-24-2334-2829 Fax: 86-24-2334-2393

China - Shenzhen

Tel: 86-755-8203-2660 Fax: 86-755-8203-1760

China - Wuhan

Tel: 86-27-5980-5300 Fax: 86-27-5980-5118

China - Xian

Tel: 86-29-8833-7252 Fax: 86-29-8833-7256

China - Xiamen

Tel: 86-592-2388138 Fax: 86-592-2388130

China - Zhuhai Tel: 86-756-3210040

Fax: 86-756-3210049

#### ASIA/PACIFIC

India - Bangalore

Tel: 91-80-3090-4444 Fax: 91-80-3090-4123

India - New Delhi

Tel: 91-11-4160-8631 Fax: 91-11-4160-8632

India - Pune

Tel: 91-20-2566-1512 Fax: 91-20-2566-1513

Japan - Yokohama

Tel: 81-45-471- 6166 Fax: 81-45-471-6122

Korea - Daegu

Tel: 82-53-744-4301 Fax: 82-53-744-4302

Korea - Seoul

Tel: 82-2-554-7200 Fax: 82-2-558-5932 or 82-2-558-5934

Malaysia - Kuala Lumpur

Tel: 60-3-6201-9857 Fax: 60-3-6201-9859

Malaysia - Penang

Tel: 60-4-227-8870 Fax: 60-4-227-4068

Philippines - Manila

Tel: 63-2-634-9065 Fax: 63-2-634-9069

Singapore

Tel: 65-6334-8870 Fax: 65-6334-8850

Taiwan - Hsin Chu

Tel: 886-3-6578-300 Fax: 886-3-6578-370

Taiwan - Kaohsiung Tel: 886-7-213-7830

Fax: 886-7-330-9305

Taiwan - Taipei

Tel: 886-2-2500-6610 Fax: 886-2-2508-0102

Thailand - Bangkok

Tel: 66-2-694-1351 Fax: 66-2-694-1350

#### **EUROPE**

Austria - Wels

Tel: 43-7242-2244-39 Fax: 43-7242-2244-393 Denmark - Copenhagen

Tel: 45-4450-2828 Fax: 45-4485-2829

France - Paris

Tel: 33-1-69-53-63-20 Fax: 33-1-69-30-90-79

**Germany - Munich** 

Tel: 49-89-627-144-0 Fax: 49-89-627-144-44

Italy - Milan

Tel: 39-0331-742611 Fax: 39-0331-466781

Netherlands - Drunen

Tel: 31-416-690399 Fax: 31-416-690340

Spain - Madrid

Tel: 34-91-708-08-90 Fax: 34-91-708-08-91 **UK - Wokingham** 

Tel: 44-118-921-5869 Fax: 44-118-921-5820

08/04/10